

In re Patent Application of:
AMMAR ET AL.
Serial No. 10/647,681
Filing Date: August 25, 2003

In the Claims:

Claims 1-20 (PREVIOUSLY CANCELLED)

21. (CURRENTLY AMENDED) A method for transferring radio frequency (RF) signals greater than about 500 MHz between first and second cooperating circuit boards, which comprises:

positioning a housing member against the ~~first~~ first printed circuit board, said housing member including a plurality of clip receiving slot slots and a conductive clip member received within ~~the clip~~ each clip receiving slot, ~~the clip member~~ each clip member including only opposing free ends that extend beyond the housing member which can make electrical contact such that one free end of ~~the~~ each clip member ~~engages a circuit~~ member engages circuits on the first printed circuit board;

biasing the other free ~~end of the~~ end of each clip member into connection with a circuit of a second printed circuit board such that a center clip member interconnects a radio frequency (RF) signal line and adjacent clip members interconnect ground lines and other clip members adjacent to the ground lines interconnect DC signal lines; and

transferring RF signals between the boards via the conductive clip member engaging RF signal lines; and

transferring DC signals via the clip members interconnecting DC signal lines, and transferring ground connections via the clip members interconnecting ground lines such that the clip members interconnecting ground lines provide isolation and improve return loss.

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22. (PREVIOUSLY PRESENTED) A method according to claim 21, and further comprising the step of transferring ground signals using conductive clip members positioned on either side of the conductive clip member that transfers RF signals.

23. (PREVIOUSLY PRESENTED) A method according to claim 21, and further comprising the step of soldering the end of the conductive clip member engaging the first printed circuit board.

24. (ORIGINAL) A method according to claim 21, wherein the connector is solderless on at least one end.

25. CANCELLED

26. (PREVIOUSLY PRESENTED) A method according to claim 21, and further comprising the step of positioning a plurality of housing members adjacent to each other and transferring ground signals using conductive clip members positioned on either side of the conductive clip member that transfers RF signals.

27. (ORIGINAL) A method according to claim 21, and further comprising the step of transferring RF signals at no less than 4 GHz.

28. (PREVIOUSLY PRESENTED) A method according to claim 21, wherein the conductive clip member comprises one or more surface mount pressure contacts.

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29. (PREVIOUSLY PRESENTED) A method according to claim 21, and further comprising the step of mixing the RF signals with a carrier frequency for passing through a conductive clip member.

30. (CURRENTLY AMENDED) A method of transferring RF signals greater than about 500 MHz between first and second cooperating printed circuit boards comprising:

providing a conductive clip ~~member that has~~ members that each have only two opposing ends for making electrical contact between two boards, without use of connecting wires between the boards such that the conductive clip member ends engage respective boards, wherein a center clip member interconnects a radio frequency (RF) signal line and adjacent clip members interconnect ground lines, and other clip members adjacent to the ground lines interconnect DC signal lines; and

transferring RF signals between the boards via the conductive clip member engaging a RF signal line; and

transferring DC signals via the clip members interconnecting DC signal lines, and transferring ground connections via the clip members interconnecting ground lines such that the clip members interconnecting ground lines provide isolation and improve return loss.

31. (ORIGINAL) A method according to claim 30, and further comprising the step of transferring the RF signals at no less than 4 GHz.

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32. (PREVIOUSLY PRESENTED) A method according to claim 30, wherein the conductive clip member is solderless on at least one end.

33. (PREVIOUSLY PRESENTED) A method according to claim 30, wherein the conductive clip member comprises one or more surface mount contacts.

34. (ORIGINAL) A method according to claim 30, and further comprising the step of mixing the RF signals with a carrier frequency and/or other RF processing signals that add functionality.

35. (PREVIOUSLY PRESENTED) A method according to claim 30, and further comprising the step of transferring ground signals using conductive clip members positioned on either side of the conductive clip member that transfers RF signals.

36. (CURRENTLY AMENDED) A connector system for transferring RF signals greater than about 500 MHz between first and second cooperating printed circuit boards, comprising:

a housing member having a plurality of clip receiving slot slots and a conductive clip member received ~~with the~~ in each clip receiving slot, wherein ~~the~~ each conductive clip member includes only opposing free ends that extend beyond the housing member which can make electrical contact wherein one free end of ~~the conductive~~ a conductive clip member engages a circuit on the first printed circuit board and the other free end of ~~the conductive~~ a conductive clip member is biased into

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connection with a circuit of the second printed circuit board wherein a center clip member interconnects a radio frequency signal line and adjacent clip members interconnect ground lines, and other clip members adjacent to the ground lines interconnect DC signal lines such that RF signals are transferred via the conductive clip member interconnecting a RF signal line between the first and second printed circuit boards and DC signals are transferred via the clip members interconnecting the DC signal lines and ground connections are transferred via the clip members interconnecting ground lines such that the clip members interconnecting ground lines provide isolation and improve return loss.

37. (ORIGINAL) A connector system according to claim 36, wherein said RF signals are transferred at frequencies no less than 4 GHz with very low losses.

38. (PREVIOUSLY PRESENTED) A connector system according to claim 36, wherein the conductive clip member is solderless on at least one end.

39. (PREVIOUSLY PRESENTED) A connector system according to claim 36, wherein the conductive clip member comprises one or more surface mount pressure contacts.

40. (ORIGINAL) A connector system according to claim 36, wherein RF signals are mixed with a carrier frequency and/or RF processing signals.